



MULTILAYER CERAMIC CAPACITORS

3-Terminal Capacitor Series (FT)

Feed Through Type 0805 Size (10V to 50V) X7R Dielectric

PASSIVE S

Halogen Free & RoHS Compliance

Preliminary spec

*Contents in this sheet are subject to change without prior notice.



1. DESCRIPTION

This product specification is applied to 3-terminal Capacitor for FT Series used for General Electronic equipment. WTC capacitor Feed Through type are developed to offer designers the opportunity to lower placement costs increase assembly line output through lower component count per board.

2. FEATURES

- a. High density mounting due to mounting space saving.
- b. Mounting cost saving.
- c. Increased throughput.

3. APPLICATIONS

- a. For use as a bypass for digital and analog signal line noise
- b. Computer motherboards and peripherals.
- c. The other common electronic circuits.

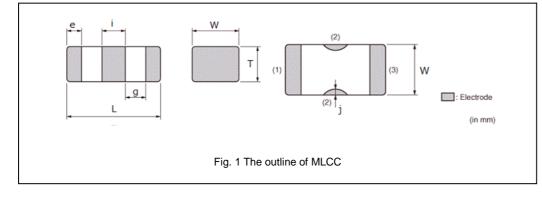
4. HOW TO ORDER

| <u>FT</u> | <u>21</u> | <u>B</u> | <u>105</u> | <u>M</u> | <u>160</u> | <u>C</u> | Ī |
|----------------------------------|------------------------|------------|--|------------------|---|--------------------|-------------|
| Series | <u>Size</u> | Dielectric | Capacitance | Tolerance | Rated voltage | Termination | Packaging |
| FT= Feed Through Capacitor | 21 =0805 (2012) | B=X7R | Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 0R5=0.5pF 1R0=1.0pF $105=10x10^5$ =1000nF=== =1µF | 一日 | Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 100=10 VDC 160=16 VDC 250=25 VDC 500=50 VDC | C =Cu/Ni/Sn | T=7" reeled |





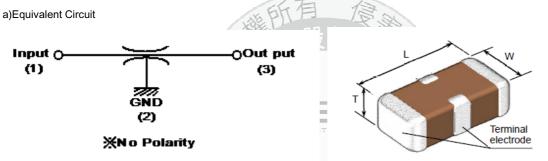
5. EXTERNAL DIMENSIONS



| Brand | L (mm) | W (mm) | T (mm)/Sym | ibol | e (mm) | g (mm) | i (mm) | j(mm) |
|-------|-----------|-----------|------------|------|-----------|-----------|-----------|-----------|
| 0805 | 2.00±0.20 | 1.25±0.10 | 0.85±0.10 | т | 0.30±0.20 | 0.40±0.20 | 0.60±0.20 | 0.25±0.20 |

Reflow soldering process only.

6. Rated value



| | | 01 | | | | | |
|--------------|------------------------|--------------------------|---------------------|-----------------------|---------------|--------------------------|-----------------------|
| WTC PART NO. | Nominal Capacitance | Capacitance Tolerance | DC Rated Voltage | Rated Current (mA) | DC Resistance | Insulation Resistance | Operating Temp. Range |
| FT21B103M500 | 10 nF | ±20% | DC50 V_0 | 2A(DC) | 0.03Ωmax | 1000MΩmin | -55 to 125°C |
| FT21B223M500 | 22 nF | ±20% | DC50 V | 2A(DC) | 0.03Ωmax | 1000MΩmin | -55 to 125°C |
| FT21B473M500 | 47 nF | ±20% | DC50 V | 2A(DC) | 0.03Ωmax | 1000MΩmin | -55 to 125°C |
| FT21B104M250 | 0.1 uF | ±20% | DC25 V | 2A(DC) | 0.03Ωmax | 1000MΩmin | -55 to 125°C |
| FT21B224M160 | 0.22 uF | ±20% | DC16 V | 2A(DC) | 0.03Ωmax | 1000MΩmin | -55 to 125°C |
| FT21B474M160 | 0.47 uF | ±20% | DC16 V | 2A(DC) | 0.03Ωmax | 1000MΩmin | -55 to 125°C |
| FT21B105M160 | 1 uF | ±20% | DC16 V | 4A(DC) | 0.02Ωmax | 500MΩmax | -55 to 125°C |

* Measured at the condition of 30~70% related humidity.

X7R/X6S/X5R/X7S: Please refer to page 5 "Reliability test conditions and requirements" for detail.

** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour and then leave in ambient condition for 48±2 hours before measurement.

7. GENERAL ELECTRICAL DATA

| No | Item | Specification | Test Method |
|----|-----------------------------|--|--|
| 1 | Capacitor(Cap.) | Meet item 6. | Frequency : 1.0±0.1kHz |
| | | | Voltage : 1±0.2V(rms) |
| 2 | Insulation Resistance(I.R.) | Meet item 6 | Voltage : Rated Voltage |
| | · · · · | | Time : 2 minutes max. |
| 3 | DC Resistance | As for Direct Current spec of each product, please | Measured with 100mA max. |
| | | refer to item 6 Measuring current shall be 100mA max Rdc I | |
| 4 | Withstanding Voltage | Products shall not be damaged. | Test Voltage : Rated Voltage x 300% Time : 1 to 5 s |
| | | | Charge Current : 50 mA max. |
| 5 | Operating Temperature | Shown in item 6. | Includes self-heating |
| 6 | Storage Temperature | 5 to 40°C at 20 to 70%RH | |

* Measured at 30~70% related humidity.

X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at the conditions of 25℃ ambient temperature.

** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 48±2 hours before measurement.

8. CAPACITANCE RANGE

| | | | X | | |
|----|-----------------------|----|----|---------------|---------|
| | SIZE Inch (mm) | | | [21 (2012) | |
| | DIELECTRIC | | X | 7R | |
| RA | ATED VOLTAGE (VDC) | 10 | 16 | 25 | 50 |
| | 10nF (103) | Т | T | | Т |
| | 22nF (223) | Т | Т | J | Т |
| | 47nF (473) | Т | Т | T. | 67h |
| | 0.10µF (104) | Т | Т | Ť. | Tra |
| | 0.22µF (224) | Т | Т | | SCHNOIT |
| | 0.47µF (474) | Т | Т | | |
| | 1µF (105) | Т | Т | | |

1. The letter in cell is expressed the symbol of product thickness.

9. PACKAGING DIMENSION AND QUANTITY

| SIZE Inch (mm) | Thickness/Symbol (mm) | | Packing | | Packing Unit |
|-------------------|--------------------------|---|------------------|----------------|--------------|
| 0805 | 0.85±0.10 | т | 180mm Reel PAPER | 4000 pcs./Reel | |

Unit: pieces

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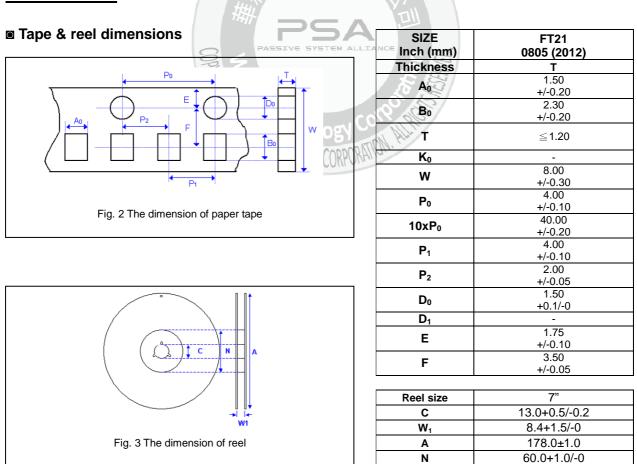
10. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

| No. | ltem | | Test Condition | | Requirements | | |
|-----|----------------|--------------------|--|----------------------|---|-------------------------------|--|
| 1. | Appearance | Visual Inspecti | on and measured with S | lide Calipers. | * No remarkable defect. * Dimensions to conform to individual specification sheet. | | |
| | | | | | | | |
| | and | | | | | | |
| | Dimensions | | | | | | |
| 2. | Capacitance | Frequency : 1.0 | 0±0.1kHz | | * Shall not exceed the limits g | iven in the detailed spec. | |
| | | Voltage : 1±0.2 | ?V(rms) | | | | |
| 3. | Solder ability | * Solder temper | ature: 240±3℃ | | 90% min. coverage of all met | alized area. | |
| | | * Dipping time: 2 | 2±0.5 sec. | | | | |
| | | | | | | | |
| 4. | Resistance to | | ature: 270±5℃ | | Meet table 1. | | |
| | Soldering Heat | | | | Table 1 | | |
| | | | 0 to 150℃ for 1 minute be | efore imme rse the | Appearance | No damaged | |
| | | capacitor in a e | | | Cap. Change | Within±7.5% | |
| | | | easurement (Class II only | | I.R. | Meet the initial rated value. | |
| | | | then set for 48±4 hrs at ro | | DC Resistance | 0.05Ω max | |
| | | | surement to be made after for 48±4 hrs at room temp | | * 25% max. leaching on each | edge. | |
| 5. | Bending Test | | red on the glass-epoxy su | 2 | Meet table2. | | |
| | | (100×40×1.0mn | ı). | | | | |
| | | Table 2 Deflecti | on : 2 mm | 古阳份; | Table2 | | |
| | | Keeping Time : | 30 s Pressu | ire jig | Appearance | No damaged | |
| | | | R5 F | | Cap. Change | Within±7.5% | |
| | | Ľ | | | DC Resistance | 0.05Ω max | |
| | | (| 45 45 Product | | | | |
| 6. | Adhesive | * Pressurizing for | orce : S | | * No remarkable damage or re | emoval of the terminations. | |
| | Strength of | 5N (≤0603) and | Z | | | | |
| | Termination | * Test time: 30± | 1 sec. | | | | |
| 7. | Vibration | * Vibration frequ | iency: 10~55 Hz/min. | | Meet Table 3. | | |
| | Resistance | * Total amplitude | e: 1.5mm | Chhology | Table3 | | |
| | | * Test time: 6 hr | s. (Two hrs each in three r | mutually | Appearance | No damaged | |
| | | perpendicular d | irections.) | WOLDGY (ORPOR | Capacitance | Meet the initial rated value | |
| | | *Before initial m | easurement (Class II only |): To apply de-aging | DC Resistance | 0.05Ω max | |
| | | | then set for 48±4 hrs at ro | | | | |
| | | | nent to be made after de-a | aging at 150°C for | | | |
| | | 1hr then set for | 48±4 hrs at room temp. | | | | |
| 8. | Temperature | Conduct the 10 | cycles according to the te | mperatures and time | Meet table 4. | | |
| | Cycling | | _ | | Table 4 | | |
| | | Step | Temp. (°C) | Time (min.) | Appearance | No damaged | |
| | | | pperating temp. +0/-3 | 30±3 | Cap. Change | Within±7.5% | |
| | | | temp. operating temp. +3/-0 | 2~3 30±3 | I.R. | Meet the initial rated value. | |
| | | | temp. | 2~3 | DC Resistance | 0.05Ω max | |
| | | ·ł | | | | | |
| | | *Before initial m | easurement (Class II only |): To apply de-aging | | | |
| | | at 150℃ for 1hr | then set for 48±4 hrs at ro | oom temp. | | | |
| | | * Cap. / I.R. Me | asurement to be made afte | er de-aging at 150℃ | | | |
| | | for 1hr then set | for 48±4 hrs at room temp |). | | | |
| | | Total of 10 cycle | 6 | | • | | |



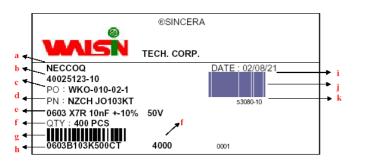
| No. | ltem | Test Condition | Requ | irements | |
|-----|--------------|--|---|----------------------------------|--|
| 9. | Humidity | * Test temp.: 40±2℃ | Then measured after exposure in the room condition for 48±4 hours | | |
| | (Damp Heat) | * Humidity: 90~95% RH | If it's doubt, the measuring has | to be done after 1 hours curing | |
| | Steady State | * Test time: 500+24/-0hrs. | at 150+0 / -10℃ and 48±4 hour | s storage. | |
| | | *Before initial measurement (Class II only): To apply de-aging | Meet Table5. | | |
| | | at 150°C for 1hr then set for 48±4 hrs at room temp . | Table5 | | |
| | | * Cap. / I.R. Measurement to be made after de-aging at $150 \ensuremath{\mathbb{C}}$ | Appearance | No damaged | |
| | | for 1hr then set for 48±4 hrs at room temp. | Cap. Change | Within±12.5% | |
| | | | I.R. | 50Ω·F min | |
| | | | DC Resistance | 0.05Ω max | |
| | | | | | |
| 10. | High | Temperature : Maximum Operating Temperature ± 2 °C | | | |
| | Temperature | Test Voltage : Rated Voltage x 200% | Then measured after exposure | e in the room condition for 48±4 | |
| | Load | Charge Current : 50 mA max. | hours. | | |
| | (Endurance) | Time : 1000+48 / -0 hours | If it's doubt, the measuring has to be done after 1 hours curing | | |
| | | * Cap. / I.R. Measurement to be made after de-aging at 150° C | at 150+0 / -10℃ and 48±4 hours storage. Meet Table6. | | |
| | | for 1hr then set for 48±4 hrs at room temp | | | |
| | | | Table6 | | |
| | | | Appearance | No damaged | |
| | | | Cap. Change | Within±12.5% | |
| | | 公有 1 | L.R. | 50Ω·F min | |
| | | HE HE KIN | DC Resistance | 0.05Ω max | |

APPENDIXES



ASC_Feed_Through_FT_026A_AS

Example of customer label



*Customized label is available upon request

- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

Constructions

| | | | ALE ALE | |
|-----|------------------|--------------|------------------------------|---------------------------------|
| No. | Name | | X7R- (-) | |
| 1 | Ceramic material | | BaTiO ₃ based | 3 |
| 2 | Inner electrode | | HILL SK NI | |
| 3 | | Inner layer | Pusa P | |
| 4 | Termination | Middle layer | A PASSIVENEYSTEM ALLIANCE | Φ |
| 5 | | Outer layer | Sn Sn | Fig. 5 The construction of MLCC |
| | | | in the chology Corport Hills | |

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Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

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Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.

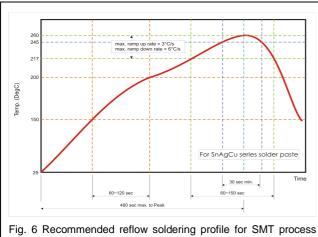


Fig. 6 Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.

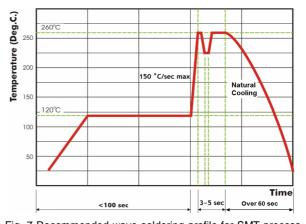


Fig. 7 Recommended wave soldering profile for SMT process with SnAgCu series solder.

